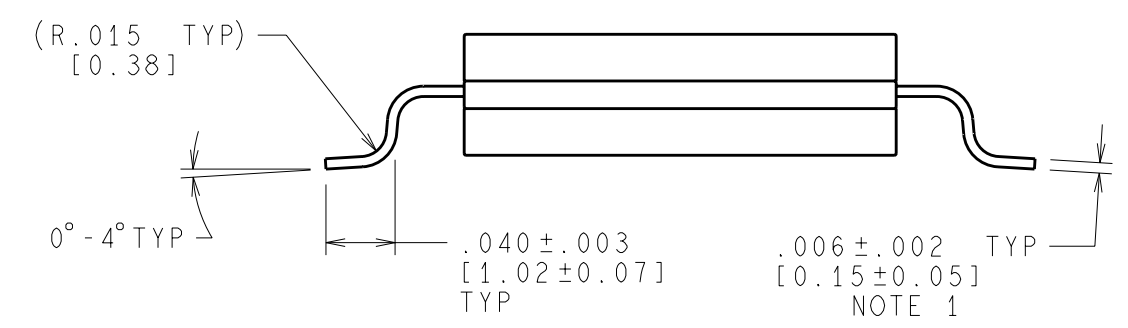
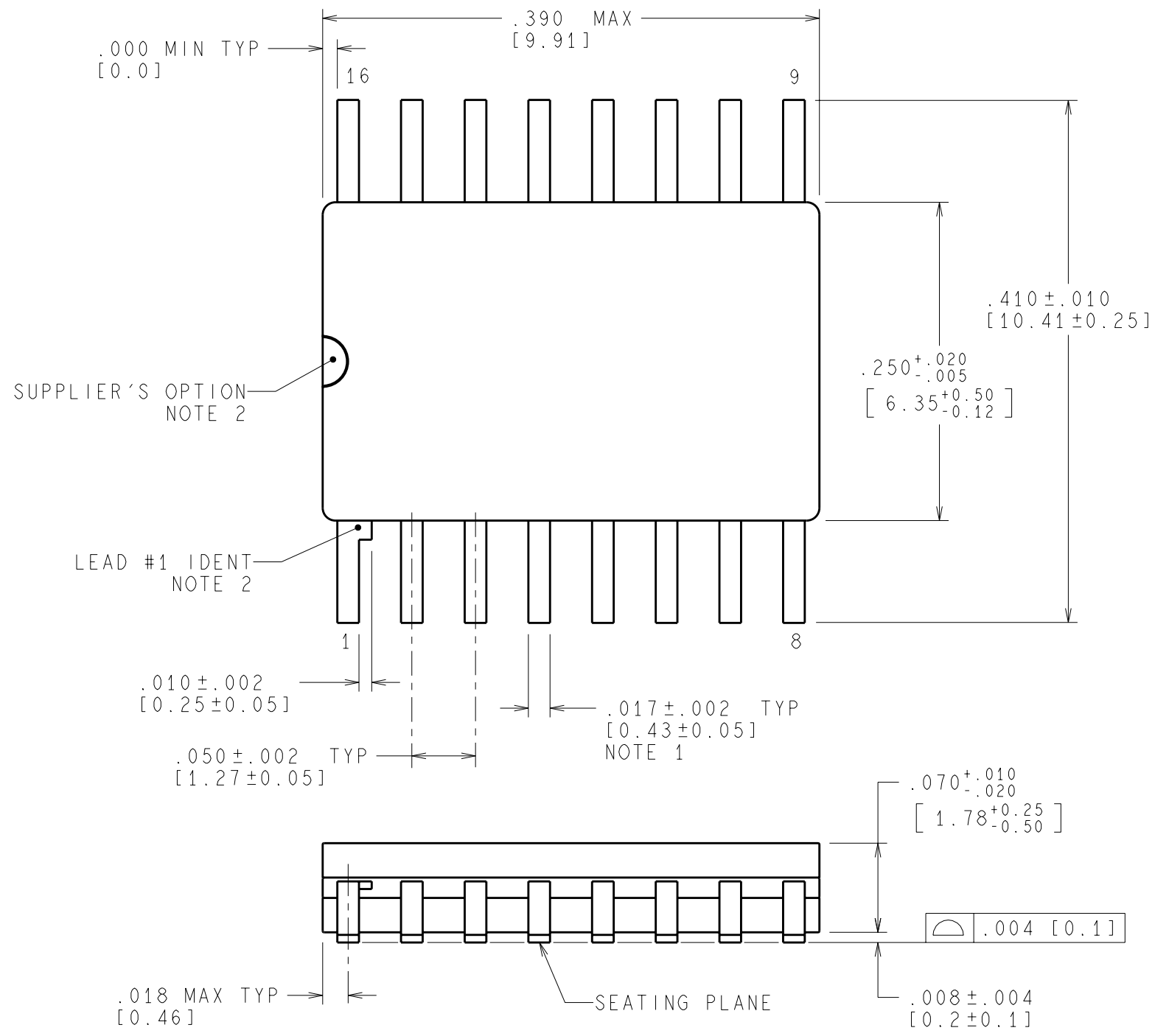


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11376	02/29/1996	MS/KH
B	LD PITCH TOL WAS $\pm .005$; CHANGE LD RADIUS TO REF DIM; REMOVE THE OTHER R. $0.06 \pm .002$; DIM $.040 \pm .003$ WAS $.037 \pm .003$	11443	04/19/1996	MS/KH
C	R $.015[0.38]$ WAS R $.006[0.15]$	11840	10/08/1997	TL/KH
D	$.000$ MIN WAS $.005$ MIN; UPDATE TITLE; CHANGE TO B SIZE FORMAT	1535	07/13/2004	TL/CBS



NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-PRF-38535 TO A MINIMUM THICKNESS OF 200 MICRONS/ 5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASE METAL OR Sn PLATE. MAXIMUM LIMIT MAY BE INCREASED BY .003 IN/ 0.08mm AFTER LEAD FINISH APPLIED.
- LEAD 1 IDENTIFICATION SHALL BE:
 - A NOTCH OR OTHER MARK WITHIN THIS AREA.
 - A TAB ON LEAD 1, EITHER SIDE.
- NO JEDEC REGISTRATION AS OF JULY 2004.

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

MIL-PRF-38535
CONFIGURATION CONTROL

APPROVALS	DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090
DRAWN MARTA SUCHY	02/29/1996	
DFTG. CHK. MARTA SUCHY	07/13/2004	
ENGR. CHK. ALVIN CB SIM	07/13/2004	
PROJECTION 		SCALE NTS
SIZE B		DRAWING NUMBER (SC)MKT-WG16A
FORMERLY: N/A		REV D
SHEET 1 of 1		